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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1 to 7. (canceled)

Claim 8. (currently amended) A reactive hot melt composition obtained by reacting

(i) a polyol mixture comprising (1) 30 to 90% by weight of a crystalline polyester polyol having a number average molecular weight of 1,500 to 10,000, produced from at least one aliphatic dicarboxylic acid and a first aliphatic diol as main components, (2) 5 to 30% by weight of a polyester polyol having a number average molecular weight of 1,500 to 10,000, produced from at least one aromatic polycarboxylic acid and a second aliphatic polyol as main components, and

- (3) 5 to 40% by weight of a polycarbonate polyol having a number average molecular weight of 500 to 5,000, and
- (ii) a polyisocyanate,

wherein a molar ratio of the OH group of the polyol mixture to the NCO group of the polyisocyanate is 1:1.7 to 1:2.5_

the composition has a viscosity at 120°C of 200 to 40,000 cps, and the composition is used as a molded product in the fields of an electric and electronic parts producing industry and a semiconductor parts producing industry.

- (previously presented) A molded product prepared from the reactive hot melt composition according to Claim 8.
- (previously presented) A molded product which is Claim 10. obtained by injecting the reactive hot melt composition according to Claim 8 into a closed mold, cooling the reactive hot melt composition, removing the composition from the mold, and then, curing the composition by moisture in the air.

Claim 11. (previously presented) A molded product according to Claim 10, wherein the molded product is obtained by providing an inserting material in the closed mold and integrally molding the reactive hot melt composition with the inserting material.

Claim 12. (canceled)

Claim 13. (original) A molded product according to Claim 11, wherein the inserting material is an electric or electronic constitutional part or a semiconductor constitutional part.

Claim 14. (previously presented) A molded product according to Claim 13, wherein the electric or electronic constitutional part or the semiconductor constitutional part is a sensor, a circuit board, an element, a switch, a wiring, a connector, a display device or a battery.

Claims 15 to 21. (canceled)

Claim 22. (previously presented) The reactive hot melt composition according to Claim 8, wherein the crystalline polyester polyol (1) produced by the aliphatic dicarboxylic acid and the first aliphatic diol as main components has a crystallinity of 30% or more, when the polyester polyol is cooled and solidified from a melting state at a cooling rate of 10°C/min and the crystallinity of which is measured by an X-ray diffraction method according to Ruland's method.

Claim 23. (previously presented) The reactive hot melt composition according to Claim 8, wherein

the crystalline polyester polyol (1) is a diol comprising the at least one aliphatic dicarboxylic acid which is a dicarboxylic acid having 6 to 12 carbon atoms, and the first aliphatic diol is a diol having 2 to 12 carbon atoms;

the polyester polyol (2) is a polyol comprising the at least one aromatic polycarboxylic acid which is selected from the group consisting of phthalic acid, terephthalic acid and isophthalic acid, and the second aliphatic polyol is a polyol having 2 to 12 carbon atoms.

Claim 24. (previously presented) The reactive hot melt composition according to Claim 23, wherein the at least one aliphatic dicarboxylic acid of (1) is selected from the group consisting of dodecanedioic acid and adipic acid; and wherein the first aliphatic diol is 1,6-hexanediol.

Claim 25. (previously presented) The reactive hot melt composition according to Claim 24, wherein the at least one aromatic polycarboxylic acid of (2) is phthalic acid; and the second aliphatic polyol is a polyester polyol comprising ethylene glycol and neopentyl glycol.

Claim 26. (previously presented) The reactive hot melt composition according to Claim 25, wherein the polycarbonate polyol (3) is a compound containing 1,6-hexanediol.

Claim 27. (previously presented) The reactive hot melt composition according to Claim 8, wherein the polyol mixture further comprises a polylactone polyol or a polyether polyol.

Claim 28. (new) The reactive hot melt composition according to Claim 8, wherein the composition has a viscosity at 120°C of 500 to 7,000 cps.